

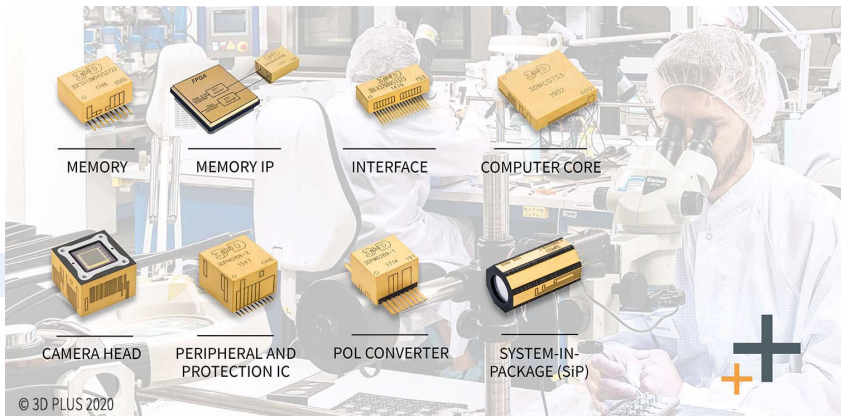
Transversal competencies



3D PLUS is the world-leading supplier of advanced high-density radiation tolerant components miniaturized with our unique 3D vertical interconnect technology. With more than 190,000 modules in space, and more than 20 years of flight heritage with no reported failure, we provide the global space industry for all types of applications: telecommunications, Earth observation, navigation, launch and manned space vehicles, science missions and constellations.

COMPETENCIES & CAPABILITIES

- Development of advanced high density 3D package and die stacking technology that allow gaining a factor of at least 10 on the weight and volume of the components comparing to other existing 2D traditional solutions.
- Design of Analog and Digital Space Radiation Hardened electronics utilizing the Radiation Intelligent product's concept.
- Manufacturing of Standard Products and custom System-in-Package for space applications.
- ESA and CNES approved capability domain and manufacturing line.
- Production of 30,000 space qualified modules per year in our facility located nearby Paris.



3D PLUS

PRODUCTS & SERVICES

3D PLUS offers a wide range of catalog radiation tolerant products including Memory and IP cores, Computer Cores, Interfaces, POL converters, Peripherals and Radiation Protection ICs and Camera heads. Custom System-In-Package (SiP) solutions are also available for our customers who want to shrink their design thanks to our State-of-the Art stacking technology and recognized design, manufacturing and test expertise.

3D PLUS products bring key advantages for our customers' electronic designs:

- High performance / high density / very high speed
- High reliability / Rugged to extremely harsh environments and Space radiations
- Extreme miniaturization / very small factor
- Space qualification and very large flight heritage.
- Long term availability

MAJOR SPACE PROJECTS & REFERENCES

Our Flight Heritage is expanding continuously with products launched in Space every month in GEO, MEO and LEO orbits, for deep space exploration missions, for satellite constellation fleets, and for governmental missions.

Our Flagship missions include Mars 2020, Mars Science Laboratory, Rosetta, New Horizons, Juno, OneWeb, AlphaSat, Sentinel, Ariane 5, ISS, Parker Solar Probe, Insight, and many more.

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TURNOVER 73 M€

WORK FORCE 300

SPACE TURNOVER 73 M€

R&D Represents 15% of Turnover.